

# YK350N04

## N-Channel Enhancement Mode Field Effect Transistor



康比電子  
HORNBY ELECTRONIC

### General Description

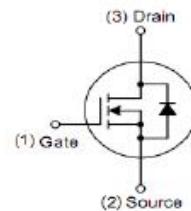
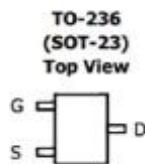
The YK350N04 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

### Application

- PWM application
- Load switch
- Power management

### Features

- $V_{DS} = 40V, I_D = 7A$   
 $R_{DS(ON)} < 60m\Omega @ V_{GS}=4.5V$   
 $R_{DS(ON)} < 35m\Omega @ V_{GS}=10V$
- High power and current handing capability
- Lead free product is acquired
- Surface mount package



### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
350N04	YK350N04	SOT-23	Ø180mm	8mm	3000 units

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	$V_{DSS}$	40	V
Gate-Source Voltage	$V_{GSS}$	$\pm 20$	V
Drain Current-Continuous $V_{GS}=4.5V$ , @ $T_a=25^\circ C$	$I_D$	7	A
Drain Current -Pulsed	$I_{DM}$	40	A
Maximum Power Dissipation @ $T_a=25^\circ C$	$P_D$	2.5	W
Single pulse avalanche energy (Note 3)	EAS	6	mJ
Operating Junction and Storage Temperature Range	$T_J$	-55 ~ +150	°C

### Thermal Characteristics

Thermal Resistance,Junction-to-Ambient (Note 1)	$R_{QJA}$	78	°C/W
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Electrical Characteristics ( $T_A=25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$\text{V}_{\text{GS}} = 0\text{V}, \text{I}_D = 250\mu\text{A}$	40	-	-	V
Zero Gate Voltage Drain Current	$\text{I}_{\text{DSS}}$	$\text{V}_{\text{DS}} = 40\text{V}, \text{V}_{\text{GS}} = 0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$\text{I}_{\text{GSS}}$	$\text{V}_{\text{GS}} = \pm 20\text{V}, \text{V}_{\text{DS}} = 0\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	$\text{V}_{\text{DS}} = \text{V}_{\text{GS}}, \text{I}_{\text{DS}} = 250\mu\text{A}$	1	-	2.5	V
Drain-Source On-State Resistance (Note 2)	$\text{R}_{\text{DS}(\text{ON})}$	$\text{V}_{\text{GS}} = 10\text{V}, \text{I}_{\text{DS}} = 4\text{A}$	-	25	35	$\text{m}\Omega$
		$\text{V}_{\text{GS}} = 4.5\text{V}, \text{I}_{\text{DS}} = 3\text{A}$	-	35	60	
Gate Resistance	$\text{R}_g$	$\text{V}_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	9.3	-	$\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$\text{C}_{\text{iss}}$	$\text{V}_{\text{GS}} = 0\text{V}$ $\text{V}_{\text{DS}} = 20\text{V}$ $f = 1.0\text{MHz}$	-	446	-	pF
Output Capacitance	$\text{C}_{\text{oss}}$		-	45	-	
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$		-	39	-	
<b>Switching Characteristics</b>						
Turn-on Delay Time (Note 4)	$\text{T}_{\text{d}(\text{on})}$	$\text{VDD} = 20\text{V}$ $\text{VGS} = 10\text{V}$ $\text{RG} = 5.0\Omega$ $\text{ID} = 3\text{A}$	-	10	-	ns
Turn-on Rise Time (Note 4)	$\text{T}_r$		-	8	-	
Turn-Off Delay Time (Note 4)	$\text{T}_{\text{d}(\text{OFF})}$		-	29	-	
Turn-Off Fall Time (Note 4)	$\text{T}_f$		-	12	-	
Total Gate Charge	$\text{Q}_g$	$\text{VDD} = 20\text{V}$ $\text{VGS} = 10\text{V}$ $\text{ID} = 3\text{A}$	-	10.5	-	nC
Gate-Source Charge	$\text{Q}_{\text{gs}}$		-	1.3	-	
Gate-Drain Charge	$\text{Q}_{\text{gd}}$		-	2.5	-	
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 2)	$\text{V}_{\text{SD}}$	$\text{VGS} = 0\text{V}, \text{IS} = 7\text{A}$ $\text{T}_j = 25^\circ\text{C}$	-	-	1.2	V
Diode Forward Current	$\text{I}_s$		-	-	5	A

## Notes:

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper
2. The data tested by pulsed, pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating. The test condition is  $\text{VDD} = 25\text{V}, \text{VGS} = 10\text{V}, L = 0.1\text{mH}$
4. Guaranteed by design, not subject to production

### Typical Electrical and Thermal Characteristics

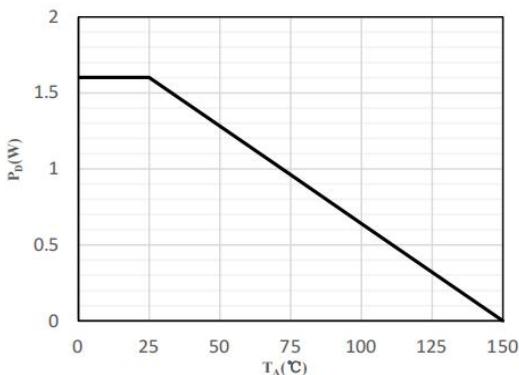


Fig 1 Power Dissipation

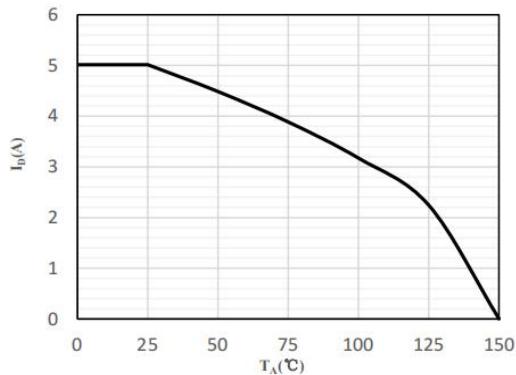


Fig 2 Drain Current

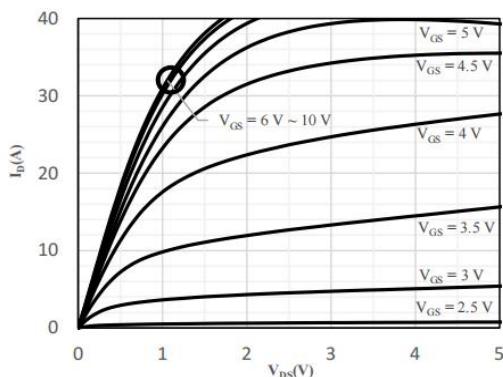


Fig 3 Typical Output Characteristics

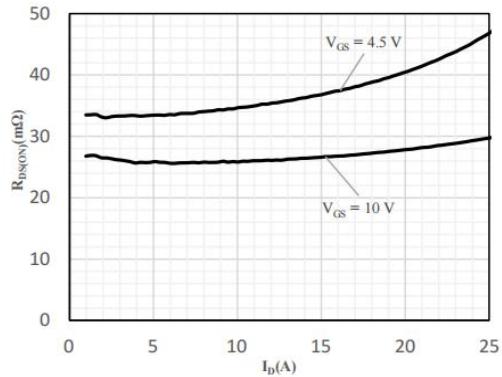


Fig 4 On-Resistance vs. Drain Current and Gate Voltage

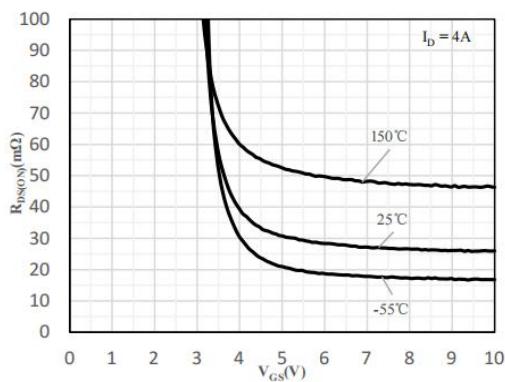


Fig 5 On-Resistance vs. Gate-Source Voltage

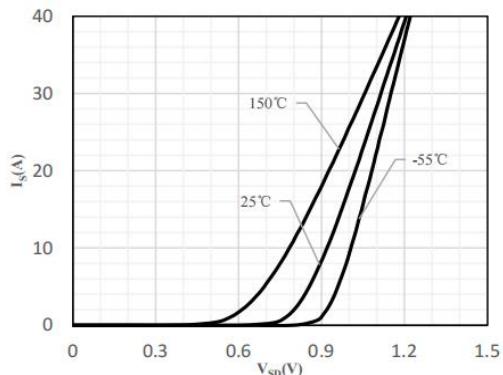


Fig 6 Body-Diode Characteristics

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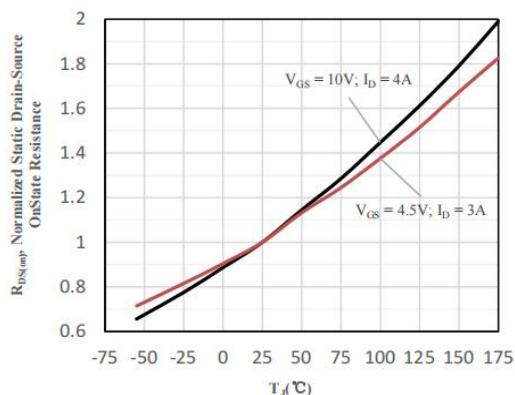


Fig 7 Normalized On-Resistance vs. Junction Temperature

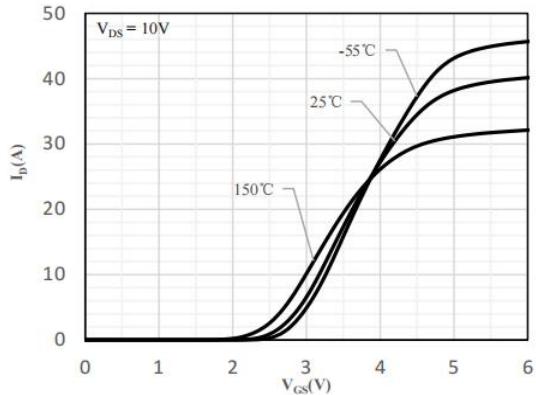


Fig 8 Transfer Characteristics

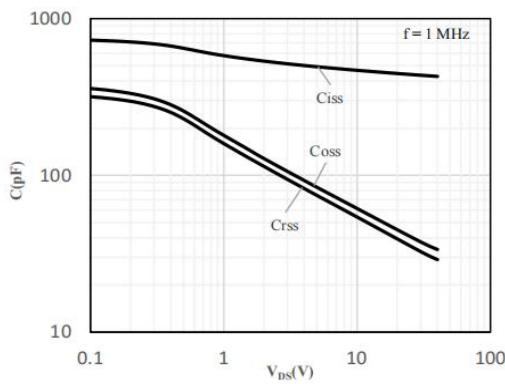


Fig 9 Capacitance Characteristics

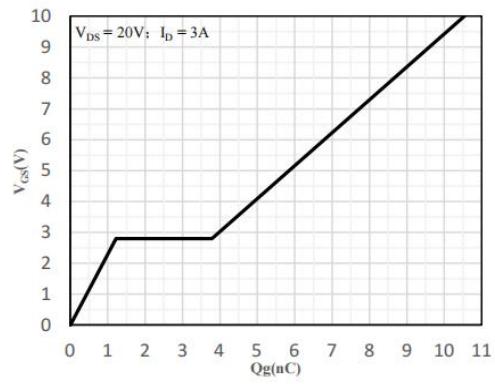


Fig 10 Gate-Charge Characteristics

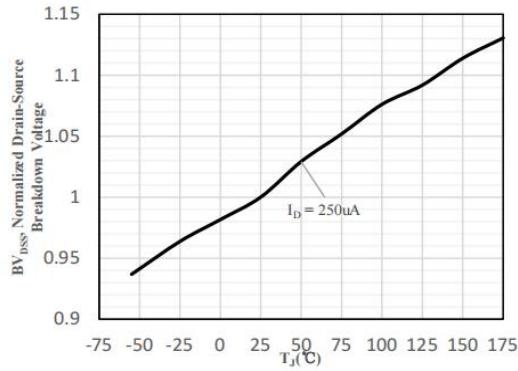


Fig 11 Normalized Breakdown Voltage vs. Junction Temperature

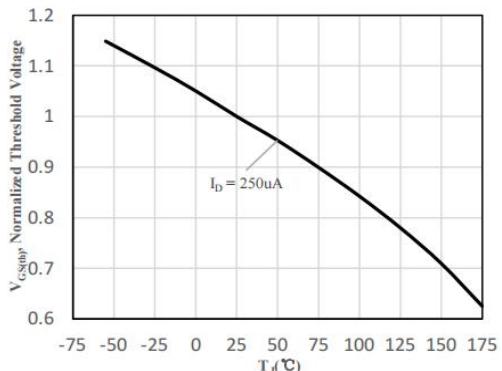
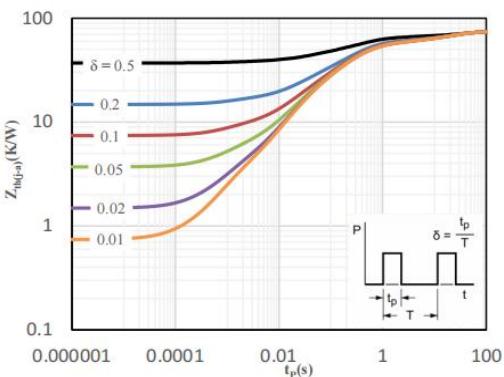
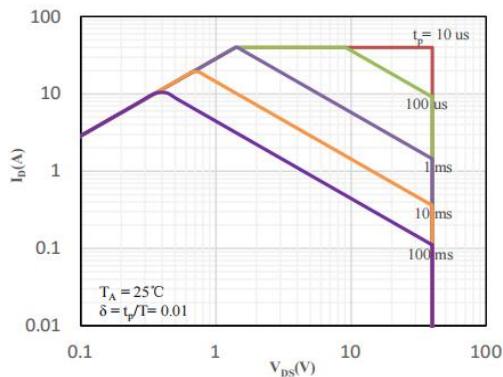


Fig 12 Normalized V<sub>GS(th)</sub> vs. Junction Temperature



### SOT-23 Package Information

